



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : 10/500,873 Confirmation No. : 1173
First Named Inventor : Masahide HAYASHI
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TC/A.U. : 2855
Examiner : Andre J. Allen
Docket No. : 056205.55095US
Customer No. : 23911

Title : Pressure Sensor, Flowmeter Electronic Component, and Method for Manufacturing the Same

REPLY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This Reply is filed in response to the Office Action dated April 5, 2006.

Each of independent claims 15 and 18 is rejected under 35 U.S.C. 102, along with claims 17 and 20, as anticipated by Japanese Patent Publication 2001-116639 to Saito et al. Reconsideration is requested.

The Saito et al. publication discloses integrally molding a resin material casing 3 with a lead terminal formed by a metallic terminal or lead member 4, and placing a sensor chip 1 in the resin material casing 3. Seal resin 8, formed of a gel or adhesive with a relatively high hardness, is thereafter filled into a penetration region, at which the lead terminal 4 projects into the resin material casing 3. The Saito et al. publication also teaches that the seal resin 8 is potted and subjected to void-removing treatment, and then subjected to heat curing. It is therefore apparent that the seal resin 8 is a thermosetting resin.